**MCM6265**

8K x 9 Bit Fast Static RAM

The MCM6265 is fabricated using Motorola's high-performance silicon-gate CMOS technology. Static design eliminates the need for external clocks or timing strobes, while CMOS circuitry reduces power consumption and provides for greater reliability.

This device meets JEDEC standards for functionality and pinout, and is available in plastic dual-in-line and plastic small-outline J-leaded packages.

- Single 5 V ±10% Power Supply
- Fully Static — No Clock or Timing Strobes Necessary
- Fast Access Times: 15, 20, 25 and 35 ns
- Equal Address and Chip Enable Access Times
- Output Enable ($\overline{G}$) Feature for Increased System Flexibility and to Eliminate Bus Contention Problems
- Low Power Operation: 110 –140 mA Maximum ac
- Fully TTL-Compatible — Three-State Output

5
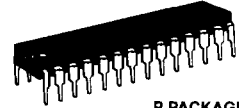
P PACKAGE
300-MIL PLASTIC
CASE 710B-01
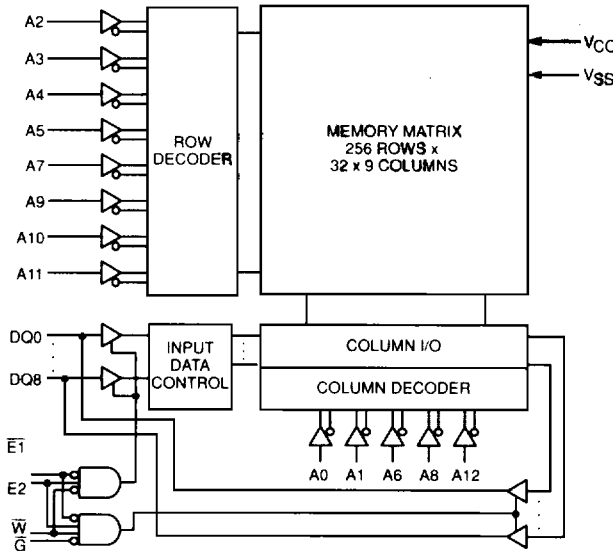
NJ PACKAGE
300-MIL SOJ
CASE 810B-03

BLOCK DIAGRAM

PIN ASSIGNMENT

A8	1 ●	28	V_CC
A7	2	27	$\overline{W}$
A6	3	26	E2
A5	4	25	A9
A4	5	24	A10
A3	6	23	A11
A2	7	22	$\overline{G}$
A1	8	21	A12
A0	9	20	$\overline{E1}$
DQ0	10	19	DQ8
DQ1	11	18	DQ7
DQ2	12	17	DQ6
DQ3	13	16	DQ5
V_SS	14	15	DQ4

PIN NAMES

A0—A12	Address Input
DQ0—DQ8	Data Input/Data Output
$\overline{W}$	Write Enable
G	Output Enable
$\overline{E1}$, E2	Chip Enable
V_CC	Power Supply (+ 5 V)
V_SS	Ground

TRUTH TABLE (X = don't care)

$\overline{E1}$	E2	$\overline{G}$	$\overline{W}$	Mode	V_{CC} Current	Output	Cycle
H	X	X	X	Not Selected	I_{SB1}, I_{SB2}	High–Z	–
X	L	X	X	Not Selected	I_{SB1}, I_{SB2}	High–Z	–
L	H	H	H	Output Disabled	I_{CCA}	High–Z	–
L	H	L	H	Read	I_{CCA}	D_{out}	Read Cycle
L	H	X	L	Write	I_{CCA}	High–Z	Write Cycle

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

This CMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage	V_{CC}	– 0.5 to + 7.0 V	V
Voltage Relative to V_{SS} For Any Pin Except V_{CC}	V_{in}, V_{out}	– 0.5 to V_{CC} + 0.5	V
Output Current	I_{out}	± 20	mA
Power Dissipation	P_D	1.0	W
Temperature Under Bias	T_{bias}	–10 to + 85	°C
Operating Temperature	T_A	0 to +70	°C
Storage Temperature — Plastic	T_{stg}	– 55 to + 125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

DC OPERATING CONDITIONS AND CHARACTERISTICS
(V_{CC} = 5.0 V ±10%, T_A = 0 to 70°C, Unless Otherwise Noted)

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage (Operating Voltage Range)	V_{CC}	4.5	5.0	5.5	V
Input High Voltage	V_{IH}	2.2	—	V_{CC} + 0.3*	V
Input Low Voltage	V_{IL}	– 0.5**	—	0.8	V

*V_{IH} (max) = V_{CC} + 0.3 V dc; V_{IH} (max) = V_{CC} + 2.0 V ac (pulse width ≤ 20 ns)
**V_{IL} (min) = – 0.5 V dc; V_{IL} (min) = – 2.0 V ac (pulse width ≤ 20 ns)

DC CHARACTERISTICS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, V_{in} = 0 to V_{CC})	$I_{lkg(I)}$	—	± 1	µA
Output Leakage Current ($\overline{E}$ = V_{IH} or $\overline{G}$ = V_{IH}, V_{out} = 0 to V_{CC})	$I_{lkg(O)}$	—	± 1	µA
Output Low Voltage (I_{OL} = 8.0 mA)	V_{OL}	—	0.4	V
Output High Voltage (I_{OH} = – 4.0 mA)	V_{OH}	2.4	—	V

POWER SUPPLY CURRENTS

Parameter	Symbol	- 15	- 20	- 25	- 35	Unit
AC Active Supply Current (I_{out} = 0 mA, V_{CC} = Max, f = f_{max})	I_{CCA}	140	130	100	110	mA
AC Standby Current ($\overline{E1}$ = V_{IH} or E2 = V_{IL}, V_{CC} = Max, f = f_{max})	I_{SB1}	40	35	30	30	mA
Standby Current ($\overline{E1}$ ≥ V_{CC} – 0.2 V or E2 ≤ V_{SS} + 0.2 V, V_{in} ≤ V_{SS} + 0.2 V, or ≥ V_{CC} – 0.2 V)	I_{SB2}	20	20	20	20	mA

CAPACITANCE (f = 1 MHz, dV = 3 V, T_A = 25°C, Periodically sampled rather than 100% tested)

Characteristic	Symbol	Max	Unit
Address and Data Input Capacitance	C_{in}	6	pF
Control Pin Input Capacitance ($\overline{E1}$, E2, $\overline{G}$, $\overline{W}$)	C_{in}	6	pF
Output Capacitance	C_{out}	7	pF

AC OPERATING CONDITIONS AND CHARACTERISTICS
(V_{CC} = 5 V ± 10%, T_A = 0 to + 70°C, Unless Otherwise Noted)

Input Timing Measurement Reference Level . . . . 1.5 V
Input Pulse Levels . . . . 0 to 3 V
Input Rise/Fall Time . . . . 5 ns

Output Timing Measurement Reference Level . . . . 1.5 V
Output Load . . . . Figure 1A Unless Otherwise Noted

READ CYCLE (See Notes 1 and 2)

Parameter	Symbol Std	Symbol Alt	−12 Min	−12 Max	−15 Min	−15 Max	−25 Min	−25 Max	−35 Min	−35 Max	Unit	Notes
Read Cycle Time	t_{AVAV}	t_{RC}	15	—	20	—	25	—	35	—	ns	3
Address Access Time	t_{AVQV}	t_{AA}	—	15	—	20	—	25	—	35	ns	
Enable Access Time	t_{ELQV}	t_{ACS}	—	15	—	20	—	25	—	35	ns	4
Output Enable Access Time	t_{GLQV}	t_{OE}	—	8	—	10	—	12	—	12	ns	
Output Hold from Address Change	t_{AXQX}	t_{OH}	4	—	4	—	4	—	4	—	ns	
Enable Low to Output Active	t_{ELQX}	t_{CLZ}	4	—	4	—	4	—	4	—	ns	5,6,7
Output Enable Low to Output Active	t_{GLQX}	t_{OLZ}	0	—	0	—	0	—	0	—	ns	5,6,7
Enable High to Output High-Z	t_{EHQZ}	t_{CHZ}	0	8	0	9	0	10	0	11	ns	5,6,7
Output Enable High to Output High-Z	t_{GHQZ}	t_{OHZ}	0	7	0	8	0	10	0	10	ns	5,6,7
Power Up Time	t_{ELICCH}	t_{PU}	0	—	0	—	0	—	0	—	ns	
Power Down Time	t_{EHICCL}	t_{PD}	—	15	—	20	—	25	—	35	ns	

NOTES:
1. $\overline{W}$ is high for read cycle.
2. $\overline{E1}$ and E2 are represented by $\overline{E}$ in this data sheet. E2 is of opposite polarity to $\overline{E}$.
3. All timings are referenced from the last valid address to the first transitioning address.
4. Addresses valid prior to or coincident with $\overline{E}$ going low.
5. At any given voltage and temperature, t_{EHQZ} max < t_{ELQX} min, and t_{GHQZ} max < t_{GLQX} min, both for a given device and from device to device.
6. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B.
7. This parameter is sampled and not 100% tested.
8. Device is continuously selected ($\overline{E1}$ = V_{IL}, E2 = V_{IH}, $\overline{G}$ = V_{IL}).

MCM6265

READ CYCLE 1 (See Note 8)

A (ADDRESS)

t_{AVAV}

t_{AXQX}

Q (DATA OUT)

PREVIOUS DATA VALID

DATA VALID

t_{AVQV}

READ CYCLE 2 (See Note 4)

A (ADDRESS)

t_{AVAV}

$\overline{E}$ (CHIP ENABLE)

t_{ELQV}

t_{EHQZ}

t_{ELQX}

t_{GHQZ}

$\overline{G}$ (OUTPUT ENABLE)

t_{GLQX}

t_{GLQV}

Q (DATA OUT)

DATA VALID

t_{AVQV}

t_{ELICCH}

t_{ELICCL}

V_{CC} SUPPLY CURRENT

I_{CC}

I_{SB}

5

AC TEST LOADS

OUTPUT

$Z_0 = 50\ \Omega$

$R_L = 50\ \Omega$

$V_L = 1.5\ V$

Figure 1A

+5 V

480 Ω

Q

255 Ω

5 pF
(INCLUDING
SCOPE AND JIG)
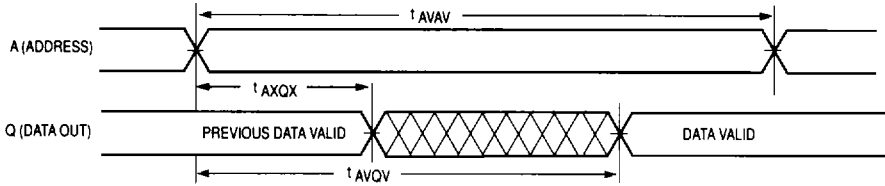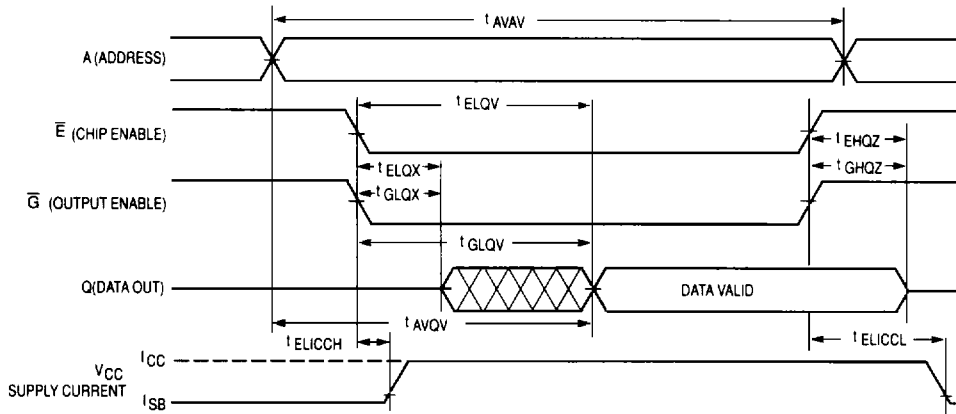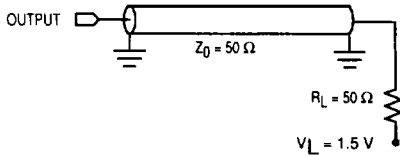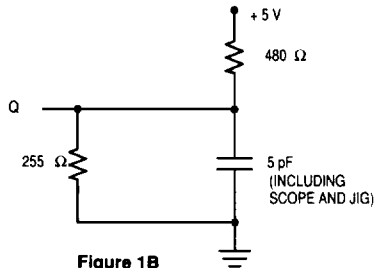
Figure 1B

TIMING PARAMETER ABBREVIATIONS

$$t\ \ X\ \ X\ \ X\ \ X$$

signal name from which interval is defined ⎯⎯⎯⎯⎯⎯⎯
transition direction for first signal ⎯⎯⎯⎯⎯⎯⎯
signal name to which interval is defined ⎯⎯⎯⎯⎯⎯⎯
transition direction for second signal ⎯⎯⎯⎯⎯⎯⎯
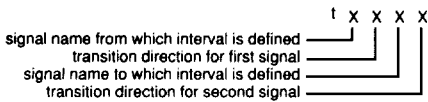
The transition definitions used in this data sheet are:
  H = transition to high
  L = transition to low
  V = transition to valid
  X = transition to invalid or don't care
  Z = transition to off (high impedance)

TIMING LIMITS

The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device output will be valid no later than that time.

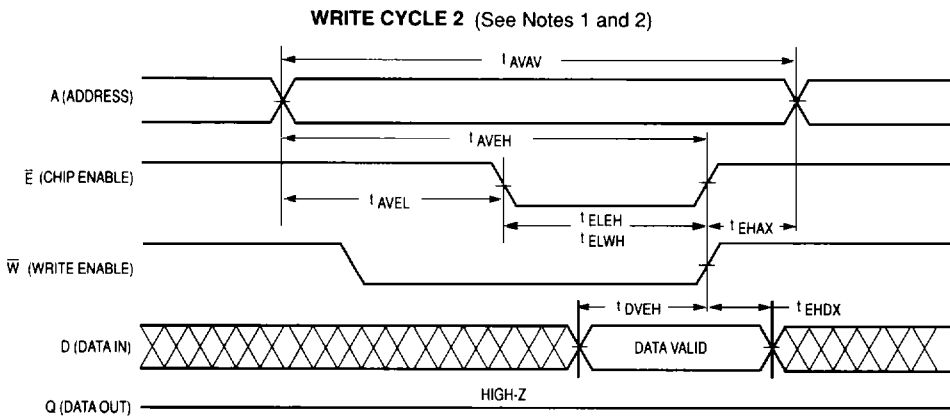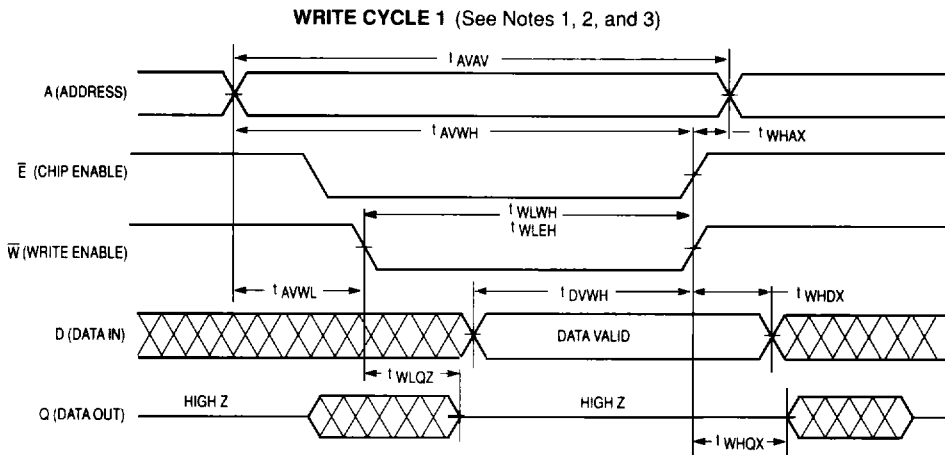**WRITE CYCLE ($\overline{W}$ Controlled)** (See Notes 1, 2, and 3)

Parameter	Symbol		-15		-20		-25		-35		Unit	Notes
	Std	Alt	Min	Max	Min	Max	Min	Max	Min	Max		
Write Cycle Time	t_{AVAV}	t_{WC}	15	—	20	—	25	—	35	—	ns	4
Address Setup Time	t_{AVWL}	t_{AS}	0	—	0	—	0	—	0	—	ns	
Address Valid to End of Write	t_{AVWH}	t_{AW}	12	—	15	—	17	—	20	—	ns	
Write Pulse Width	t_{WLWH}· t_{WLEH}	t_{WP}	12	—	15	—	17	—	20	—	ns	
Write Pulse Width, High (Output Enable devices)	t_{WLWH}· t_{WLEH}	t_{WP}	10	—	12	—	15	—	17	—	ns	5
Data Valid to End of Write	t_{DVWH}	t_{DW}	7	—	8	—	10	—	12	—	ns	
Data Hold Time	t_{WHDX}	t_{DH}	0	—	0	—	0	—	0	—	ns	
Write Low to Output High-Z	t_{WLQZ}	t_{WZ}	0	7	0	8	0	10	0	12	ns	6,7,8
Write High to Output Active	t_{WHQX}	t_{OW}	4	—	4	—	4	—	4	—	ns	6,7,8
Write Recovery Time	t_{WHAX}	t_{WR}	0	—	0	—	0	—	0	—	ns	

WRITE CYCLE ($\overline{E}$ Controlled) (See Notes 1 and 2)

Parameter	Symbol		-15		-20		-25		-35		Unit	Notes
	Std	Alt	Min	Max	Min	Max	Min	Max	Min	Max		
Write Cycle Time	t_{AVAV}	t_{WC}	15	—	20	—	25	—	35	—	ns	4
Address Setup Time	t_{AVEL}	t_{AS}	0	—	0	—	0	—	0	—	ns	
Address Valid to End of Write	t_{AVEH}	t_{AW}	12	—	15	—	20	—	25	—	ns	
Enable to End of Write	t_{ELEH}· t_{ELWH}	t_{CW}	10	—	12	—	15	—	25	—	ns	9,10
Data Valid to End of Write	t_{DVEH}	t_{DW}	7	—	8	—	10	—	15	—	ns	
Data Hold Time	t_{EHDX}	t_{DH}	0	—	0	—	0	—	0	—	ns	
Write Recovery Time	t_{EHAX}	t_{WR}	0	—	0	—	0	—	0	—	ns	

NOTES:
1. A write occurs during the overlap of $\overline{E}$ low and $\overline{W}$ low.
2. $\overline{E1}$ and E2 are represented by $\overline{E}$ in this data sheet. E2 is of opposite polarity to $\overline{E}$.
3. If $\overline{G}$ goes low coincident with or after $\overline{W}$ goes low, the output will remain in a high-impedance state.
4. All timings are referenced from the last valid address to the first transitioning address.
5. If $\overline{G} \geq V_{IH}$, the output will remain in a high-impedance state.
6. At any given voltage and temperature, t_{WLQZ} max < t_{WHQX} min, both for a given device and from device to device.
7. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B.
8. This parameter is sampled and not 100% tested.
9. If $\overline{E}$ goes low coincident with or after $\overline{W}$ goes low, the output will remain in a high-impedance state.
10. If $\overline{E}$ goes high coincident with or before $\overline{W}$ goes high, the output will remain in a high-impedance state.

WRITE CYCLE 1 (See Notes 1, 2, and 3)

A (ADDRESS)

t_{AVAV}

t_{AVWH} t_{WHAX}

Ē (CHIP ENABLE)

t_{WLWH}
t_{WLEH}

W̄ (WRITE ENABLE)

t_{AVWL} t_{DVWH} t_{WHDX}

D (DATA IN) DATA VALID

t_{WLQZ}

Q (DATA OUT) HIGH Z HIGH Z

t_{WHQX}

WRITE CYCLE 2 (See Notes 1 and 2)

A (ADDRESS)

t_{AVAV}

t_{AVEH}

Ē (CHIP ENABLE)

t_{AVEL}

t_{ELEH}
t_{ELWH} t_{EHAX}

W̄ (WRITE ENABLE)

t_{DVEH} t_{EHDX}

D (DATA IN) DATA VALID

Q (DATA OUT) HIGH-Z

5

ORDERING INFORMATION (Order by Full Part Number)

MCM 6265 X XX XX

Motorola Memory Prefix

Part Number

Package (P = 300-mil Plastic DIP, NJ = 300-mil SOJ)

Shipping Method (R2 = Tape & Reel, Blank = Rails)

Speed (15 = 15 ns, 20 = 20 ns, 25 = 25 ns)
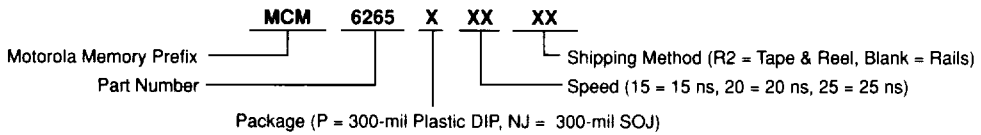
Full Part Numbers—MCM6265P15 MCM6265NJ15 MCM6265NJ15R2
MCM6265P20 MCM6265NJ20 MCM6265NJ20R2
MCM6265P25 MCM6265NJ25 MCM6265NJ25R2